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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Buie, et al.

Serial No.: 10/024,958

Confirmation No.: 3439

Filed: December 18, 2001

For: Etch Process Photolithographic  
Reticle Manufacturing with  
Improved Etch Bias

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Group Art Unit: 1765

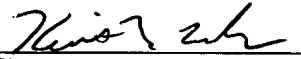
Examiner: Kin-Chan Chen

MAIL STOP AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING  
37 CFR 1.8

I hereby certify that this correspondence is being deposited on September 23, 2004 with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 23, 2004  
Date

  
Signature

Dear Sirs:

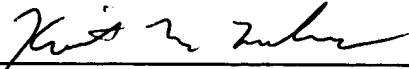
STATEMENT OF THE SUBSTANCE OF THE INTERVIEW

In response to the Interview Summary dated August 23, 2004, please enter Applicants' Statement of the Substance of the Interview.

An interview between Applicants and Examiner Chen was held on August 19, 2004. Applicants have no disagreement with the summary of the statements by the Examiner in the substance of the Examiner's Interview Summary dated August 23, 2004. Additionally, Applicants asserted in the August 19, 2004, interview, that there is no suggestion or motivation in the combined references of the method as recited by Applicants.

Agreement with respect to the claims was not reached.

Respectfully submitted,



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